

Bill of Materials

TI Designs Precision - T1PD154 - Low-Power Reference and Bipolar Voltage Conditioning Circuit Reference Design for Low-Power ADCs

Item #	Quantity	Designator	Value	Description	Manufacturer	Part Number
1	1	C1	0.15uF	CAP, CERM, 0.15uF, 16V, +/-10%, X7R, 0603	MuRata	GRM188R71C154KA01D
2	1	C2	47uF	CAP, CERM, 47uF, 6.3V, +/-20%, X5R, 0603	MuRata	GRM188R60J476M
3	3	C3, C4, C5	1uF	CAP, CERM, 1uF, 16V, +/-10%, X7R, 0603	TDK	C1608X7R1C105K
4	1	C6	10uF	CAP, CERM, 10uF, 16V, +/-20%, X7R, 1206	TDK	C3216X7R1C106M
5	1	C7	1000pF	CAP CER 1000PF 50V 20% X7R 0603	Johanson Dielectrics Inc	500X14W102MV4T
6	1	C8	0.1uF	CAP, CERM, 0.1uF, 50V, +/-10%, X7R, 0603	MuRata	GRM188R71H104KA93D
7	1	D1		DIODE TVS ARRAY 15V SOD323	Bourns	CDSOD323-T15SC
8	2	J1, J2		CONN HEADER 10POS SOCKET 2.54MM	Würth Electronics	61301011821
9	1	J3		Terminal Block, 6A, 3.5mm Pitch, 2-Pos, TH	On-Shore Technology	ED555/2DS
10	5	R1,R4, R9	100k	RES, 100k ohm, 1%, 0.1W, 0603	Vishay-Dale	CRCW0603100KFKEA
11	2	R2, R3	20.0k	RES, 20.0k ohm, 0.1%, 0.1W, 0603	Susumu Co Ltd	RG1608P-203-B-T5
12	1	R5	10.0k	RES, 10.0k ohm, 0.1%, 0.1W, 0603	Susumu Co Ltd	RG1608P-103-B-T5
13	1	R6, R7	47.0k	RES, 47.0k ohm, 0.1%, 0.1W, 0603	Susumu Co Ltd	RG1608P-473-B-T5
14	1	R8	1.00k	RES, 1.00k ohm, 0.1%, 0.1W, 0603	Yageo America	RT0603BRD071KL
15	1	SW1		SWITCH TACTILE SPST-NO 0.05A 32V	C&K Components	KSC222J LFS
16	4	TP1, TP2, TP3, TP4		Test Point, Miniature, Black, TH	Keystone	5001
17	1	U1		IC, 30 ppm/°C, 3.9 uA 3.0V-Voltage Reference	Texas Instruments	REF3330AIDCKT
18	1	U2		IC, 30 ppm/°C, 3.9 uA 1.25V-Voltage Reference	Texas Instruments	REF3312AIDCKR
19	1	U3		IC OPAMP GP 300KHZ RRO SC70-5	Texas Instruments	OPA317IDCKR

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